Certificate CN23/00003021

SGS

The management system of

Nanjing Casela Technologies Corporation Limited

Unified Social Credit Code: 91320100MA201P8U0U

Business Registration Address: Room 1519, Fuying Mansion, No. 99 Tuanjie Road, Research & Innovation Park, Jiangbei New Area, Nanjing

Business Operation Address: F9, Block C, Optoelectronic Science & Technology Park, No 6 Yuhe Road, Research & Innovation Park, Jiangbei New Area, Nanjing, Jiangsu Province, P.R. China

has been assessed and certified as meeting the requirements of

ISO 45001:2018

For the following activities

Design and manufacture of semiconductor laser chips

This certificate is valid from 10 June 2023 until 09 June 2026 and remains valid subject to satisfactory surveillance audits.

Issue 1. Certified since 10 June 2023

Certified activities performed by additional sites are listed on subsequent pages.

Jordhan M. Hell

Authorised by Jonathan Hall Global Head - Certification Services

SGS United Kingdom Ltd Rossmore Business Park, Ellesmere Port, Cheshire, CH65 3EN, UK t +44 (0)151 350-6666 - www.sgs.com











Certificate CN23/00003021, continued

SGS

Nanjing Casela Technologies Corporation Limited

ISO 45001:2018

Issue 1

Sites

Nanjing Casela Technologies Corporation Limited

Unified Social Credit Code: 91320100MA201P8U0U

Business Registration Address: Room 1519, Fuying Mansion, No. 99 Tuanjie Road, Research & Innovation Park, Jiangbei New Area, Nanjing

Business Operation Address: F9, Block C, Optoelectronic Science & Technology Park, No 6 Yuhe Road, Research & Innovation Park, Jiangbei New Area, Nanjing, Jiangsu Province, P.R. China

Design and manufacture of semiconductor laser chips

Nanjing Casela Technologies Corporation Limited

Unified Social Credit Code: 91320100MA201P8U0U

Business Registration Address: Room 1519, Fuying Mansion, No. 99 Tuanjie Road, Research & Innovation Park, Jiangbei New Area Nanjing

Business Operation Address: Plant A, No. 1 Xihua North Road, Jiangbei New Area, Nanjing, Jiangsu Province, P.R. China Design and manufacture of semiconductor laser chips









